

CALL FOR REGISTRATION

ABOUT EPTC

The 24th IEEE Electronics Packaging Technology Conference (EPTC2022) is an international event organized by the IEEE RS/EPS/EDS Singapore Chapter. It is co-sponsored by the IEEE Electronics Packaging Society (EPS). Since its inauguration in 1997, EPTC has evolved over the years into a highly reputed electronics packaging conference in Asia. EPTC 2022 will be held on 7-9 December 2022 in Singapore. It is an in-person event featuring live presentations (keynotes, panel discussion, invited presentations, workshop and professional development courses) as well as an exhibition from the industrial partners. An added highlight will be a dinner & social event at Mount Faber, the perfect spot to enjoy the sunset and panoramic views of Sentosa Island. Also, more than 200 technical and poster presentations covering all important aspects of electronics packaging listed below will be presented:

- Advanced Packaging
- TSV/Wafer Level Packaging
- Interconnection Technologies
- Emerging Technologies
- Materials and Processing
- Assembly and Manufacturing Technology
- Electrical Simulation & Characterization
- Mechanical Simulation & Characterization
- Thermal Management & Cooling Solutions
- Quality, Reliability & Failure Analysis
- Advanced Optoelectronics and Displays.
- Smart Manufacturing and Equipment Technology

Please visit www.eptc-ieee.net for the preliminary program and conference registration details

IMPORTANT DATES

Early Bird Rates	Up to 30 Sep. 2022
Standard Rates	Up to 9 Dec. 2022

VENUE: *Grand Copthorne Waterfront Hotel, Singapore*

It is located within easy reach of the Central Business District and the waterfront precincts of Robertson Quay, Singapore

KEYNOTES

Ravi Mahajan, Intel Fellow, Intel Inc. *Challenges and Opportunities in Heterogeneous Integration*

Raj Pendse, Director, Meta Reality Labs, *New Directions and Challenges in the Packaging of AR/VR hardware*

Sundar Ramamurthy, VP & GM, Applied Materials., *Materials Engineering Innovations to address Next-Gen Electronics Packaging Challenges*

[Click here for keynote abstracts and speakers' biography](#)

PANEL DISCUSSION

Chiplets as An Enabler for System Scaling

Panel Speakers: **Ravi Mahajan**, Intel; **Raj Pendse**, Meta Reality Labs; **Bernd Dielacher**, EVG Group; **Yik Yee Tan**, Yole Group

INVITED PRESENTATIONS

Fundamental Understanding of Hybrid Bonding Mechanism by Utilizing a Molecular Simulation Approach, **Minwoo Rhee**, Samsung

Pathfinding to maximization of AI/HPC/GPC System Performance, **Gamal Refai-Ahmed**, AMD

SAB for 3D and Heterogeneous Integration of Semiconductor Substrates and Devices, **Tadatomo Suga**, University of Tokyo.

Thermal and Failure Analysis of Advanced Sub-Micron Devices **Mo Shakouri**, Microsanj

Advanced Fan-Out Packaging for Chiplet Integration, **Yu-Po Wang**, SPIL

Hybrid Bonding – State-of-the-Art and Upcoming Requirements in W2W and D2W, **Bernd Dielacher**, EV Group

WORKSHOPS:

Heterogeneous Integration Roadmap (HIR)

Speakers of the HIR workshop are to be updated on the [website](#)

Packaging Education Workshop

The packaging education programs available in several countries in Asia will be presented by the respective professors

PROFESSIONAL DEVELOPMENT COURSES

PDCs taught by distinguished experts in their respective fields. Attendees of the PDCs will be offered Continuing Education Units (CEUs) or Professional Development Hours (PDHs).

PDC1: Fan-Out Packaging and Chiplet Heterogeneous Integration, **John H Lau**, Unimicron Technology Corporation

PDC2: Advanced Packaging for MEMS and Sensors, **Horst Theuss**, Infineon Technologies

PDC3: Reliability Engineering Testing Methodology and Statistical Knowledge for Qualifications of Consumer and Automotive Electronic Components, **Fen Chen**, Cruise LLC (a GM company)

PDC4: Photonic Technologies for Communication, Sensing, and Displays, **Torsten Wipiejewski**, Huawei Technologies

PDC5: Reliability of Heterogeneous Integration (HI) Systems, **SB Park**, The State University of New York (SUNY) at Binghamton and **Ganesh Subbarayan**, Purdue University

[Click here](#) for the PDC abstract and instructors' biography

Organized by



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